Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-21. (Canceled)

22. (Currently Amended) A method of producing an electroformed shaving cutter comprising:

a) providing a substrate that has an electrically conductive surface having non-zero Gaussian curvature;

b) applying a coating of electrophoretic photoresist to the electrically conductive surface by passing an electrical current therethrough;

c) exposing the photoresist to a suitable source of electromagnetic radiation through a mask that is shaped to conform to that of said electrically conductive surface of said substrate;

d) developing the photoresist; and

e) electrodepositing a metallic layer onto conductive surface regions of the substrate not coated with the photoresist.

23. (Withdrawn) A method according to claim 22, in which the substrate is of stainless steel.

24. (Previously Presented) A method according to claim 22 wherein the substrate is a body of plastics material having an electrically conductive surface coating.

25. (Withdrawn) A method according to claim 22 further comprising providing the mask with a plurality of non-elongate apertures.

26. (Withdrawn) A method according to claim 25 wherein each of the plurality of apertures has a diameter in the range 600 to 800 microns.

27. (Withdrawn) A method according to claim 22, further comprising providing the mask with a plurality of elongate apertures.

28. (Withdrawn) A method according to claim 27 wherein each of the plurality of apertures has a length of 400 to 2200 μm and a width of 400 to 800 μm.

29. (Withdrawn) A method according to claim 22 wherein the metallic layer has a varying relief pattern.

30. (Withdrawn) A method according to claim 22, wherein the mask is made of ductile metal.

31. (Withdrawn) A method according to claim 22 further comprising separating the metallic layer from the substrate by at least one of peeling and dissolution of the substrate.

32. (Withdrawn) A method of manufacturing a three-dimensional electroforming mask comprising:

providing a mandrel defining a three-dimensional surface; and

forming an electrically conductive surface pattern on the three-dimensional surface, said forming comprising etching using a laser.

33. (Withdrawn) A method according to claim 32 wherein the forming of the electrically conductive surface pattern further comprises coating an electrically conductive substrate with photoresist and selectively removing portions of the photoresist using the laser.

34. (Withdrawn) A method according to claim 32 wherein the forming of the electrically conductive surface pattern further comprises coating an electrically insulating substrate with a conductive layer, and selectively removing portions of the conductive layer using the laser.

35. (Withdrawn) A method according to claim 34 further comprising electroforming the conductive layer to a desired thickness.

36. (Withdrawn) A method according to claim 35 wherein the etching step is followed by electroforming of the conductive layer to the desired thickness.

37. (Withdrawn) A method according to claim 34, further comprising removing the coating from the substrate.

38. (Withdrawn) A method according to claim 22, wherein the surface has a non-zero Gaussian curvature.

39. (Withdrawn) A method according to claim 22, wherein the mask is made of copper.

40. (Withdrawn) A method according to claim 34 wherein the coating of electrophoretic photoresist has a substantially uniform thickness.

41. (Previously Presented) A method according to claim 22, wherein the step of applying further comprises applying the electrophoretic photoresist as a liquid.